

DIRECT RESTORATIONS

TOKUYAMA
UNIVERSAL BOND

🕒 25 SEC



Dispense one drop of each into the same dimple



Apply mixed bond



Apply weak air, then medium air until solvent evaporates



Restore with a composite resin

COMPETITORS

🕒 ≥35 SEC



Dispense one drop of bonding agent



Apply and Agitate



Air dry to evaporate solvent



Light cure bonding agent

Restore with a composite resin

INDIRECT RESTORATION

TOKUYAMA
UNIVERSAL BOND

🕒 25 SEC



Dispense one drop of each into the same dimple



Apply mixed bond.



Apply mild air.



Cementing or Intraoral repair

COMPETITORS

🕒 ≥40 SEC



Dispense and mix additional activator



Apply and Agitate



Air dry to evaporate solvent



Light cure bonding agent

Cementing or Intraoral repair